

Model		CPC304	CPC306	CPC307	CPC308	CPC309	CPC310
Compliance with PC/104-Plus™ standard:PCI (32 bit), ISA (16 bit)		V	V	V	V	V	V
CPU		AMD Geode LX800 500 MHz	DM&P Vortex86DX 600 MHz	DM&P Vortex86DX 600 MHz	Intel Atom D510/N450	Intel Atom D510 1.66 GHz	Intel Atom E3825 (Dual Core)/ E3815 (Single Core)
RAM		DDR2 SDRAM 256 MB (soldered)	DDR2 SDRAM 256 MB (soldered)	DDR2 SDRAM 256 MB (soldered)	DDR2 SDRAM 1 GB (soldered)	DDR2 SDRAM 2 GB (soldered)	DDR3L ECC SDRAM Up To 4GB (Soldered)
Graphics subsystem	Type	Integrated	No	No	Integrated	Integrated	Integrated
	Interfaces	VGA up to 1920×1440 (85 GHz 32 bit), LCD,LVDS up to 1024×768 (60 GHz 24 bit)	No	No	VGA up to 2048×1536 (60 GHz),LVDS up to 1365×768 (60 GHz 18 bit)	VGA up to 2048×1536 (60Hz), LVDS up to 1366×768 (60Hz, 18 bit)	VGA up to 2560x1600 (60 GHz), LVDS up to 1600x1200 (60 GHz 18/24 bit)
	Number of independent displays	1	-	-	2 (VGA & LVDS)	2 (VGA & LVDS)	3 (VGA & 2 x LVDS)
Storage subsystem interfaces	EIDE	1×EIDE, NAND Flash-drive 1 GB	1×EIDE, NAND Flash-drive 1 GB	1×EIDE, NAND Flash-drive 1 GB	No	No	No
	SATA	No	No	No	2×SATA II, NAND Flash-drive 4 GB	2×SATA	SLC NAND Flash Up to 8Gb Soldered, 1 x SATA II
	Removable storage devices	1×CompactFlash Type I/II	1×CompactFlash Type I/II	2×microSD	1×CompactFlash Type I/II	1×CompactFlash Type I/II	1 x CFAST Connector
Communication ports	Ethernet	2×Fast Ethernet	2×Fast Ethernet	1×Fast Ethernet	2×Gigabit Ethernet	2×Gigabit Ethernet (routed to StackPC* connector)	2×Gigabit Ethernet
	USB	2×USB 2.0	4×USB 2.0	4×USB 2.0	4×USB 2.0	2×USB 2.0, 6×USB 2.0 on StackPC	4 x USB 2.0

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Communication ports	COM-ports	2×RS-232, 2×RS-485/422 with galvanic isolation	2×RS-232, 2×RS-485/422 with galvanic isolation	2×RS-232, 2×RS-485/422 with galvanic isolation	2×RS-232, 2×RS-485/422 with galvanic isolation	2×RS-232, 2×RS-485/422 with galvanic isolation	2 x rs-232 2 x RS-485/422 with galvanic isolation
	CAN-ports	No	No	2×CAN 2.0b with galvanic isolation	No	No	No
	Digital I/O channels	8 x I/O channels, individually programmable	72 x universal digital I/O channels (+5 V)	8 x I/O channels, individually programmable	8 x I/O channels, individually programmable	8 x I/O channels, individually programmable	8 x I/O channels, individually programmable
	Analog I/O channels	No	8 x analog input channels, 2 x analog output channels (12-bit analog-to-digital converter)	No	No	No	No
	Others	PS/2, 1×LPT (SPP, EPP, ECP)	PS/2, 1×LPT (SPP, EPP, ECP)	PS/2, 1×LPT (SPP, EPP, ECP), 2×I2C	PS/2	PS/2, LPC	PS/2, SPI
Service capabilities		2 watchdog timers, real-time clock, opto-isolated reset; audio microphone, line I/O	3 watchdog timers, real-time clock, opto-isolated reset, protection against overvoltage and reverse polarity	3 watchdog timers, real-time clock, opto-isolated reset	2 watchdog timers, real-time clock, opto-isolated reset; audio microphone, line I/O	2 watchdog timers (1×Fixed, 1×Programmable), real-time clock, opto-isolated reset; audio microphone	2 watchdog timers, real-time clock, opto-isolated reset; audio, microphone

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OS support	MS-DOS, Windows XPe, Windows CE 5, Windows CE 6, Linux 2.6, QNX 6.3x	FreeDOS, MS-DOS 6.22, Windows CE 5.0, Linux 2.6, QNX 6.4	FreeDOS, MS-DOS 6.22, WinCE 5.0, Linux 2.6, QNX 6.4	FreeDOS, Windows XPe, Linux 2.6, QNX 6.5	FreeDOS; Windows XP (Embedded); Linux 2.6; QNX 6.5	Linux ; QNX ; Microsoft Windows Embedded Standard 8; Microsoft Windows Embedded Standard 7
Target power consumption *	Up to 7,5 W, depending on the version	Up to 6,5 W, depending on the version	Up to 5 W, depending on the version	Up to 15,5 W, depending on the version	TBD (To be Determined)	TBD (To be Determined)
Vibration -/Shock resistance	10g/150g	10g/150g	10g/150g	5g/100g	Up to 100g/10g depending on the version	TBD
MTBF (GOST 15150-69)	170 000 hours	170 000 hours	200 000 hours	120 000 hours	175000 hours	TBD
Operating temperature range **	-40...+85°C/ -50...+90°C	-40...+85°C	-40...+85°C/ -50...+90°C	-40...+85°C	-40...+85°C	-40...+85°C

*Target power consumption – is a power consumption for calculation of the system of heat-removal from the module. Actual power consumption depends on the load and the executed application and can be less than the specified value

**Operating temperature range depends on the device version